

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

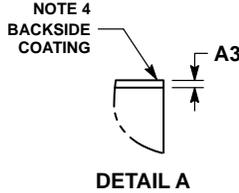
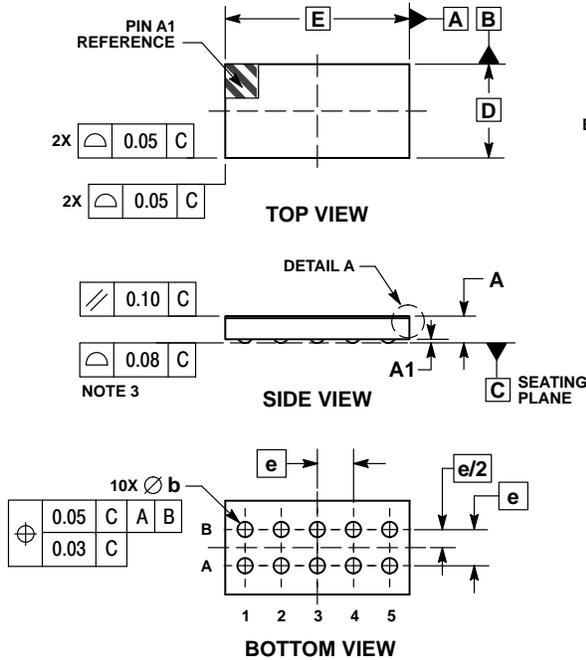
ON Semiconductor®



SCALE 4:1

WLCSP10, 1.04x2.04
CASE 567LF
ISSUE B

DATE 03 JUN 2015

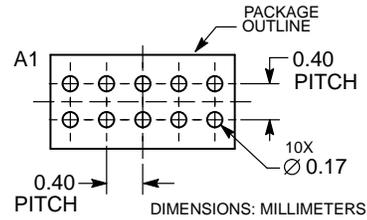


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. BACKSIDE COATING IS OPTIONAL.

DIM	MILLIMETERS	
	MIN	MAX
A	0.27	0.33
A1	0.04	REF
A3	0.025	REF
b	0.12	0.22
D	1.04	BSC
E	2.04	BSC
e	0.40	BSC

**RECOMMENDED
SOLDERING FOOTPRINT***



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
REFERENCE:		
DESCRIPTION:	WLCSP10, 1.04X2.04	PAGE 1 OF 2

